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SPEC. No. DG-087008

**ISSUE** 

Jun-27-08

### ELECTRONIC COMPONENTS AND DEVICES GROUP

### SHARP CORPORATION

### **SPECIFICATION**

### DEVICE SPECIFICATION FOR LIGHT EMITTING DIODE MODULE

MODEL No.

GW5BNF15L10

Specified for

## Reference

### CUSTOMERS' APPROVAL

Date

By

PRESENTED

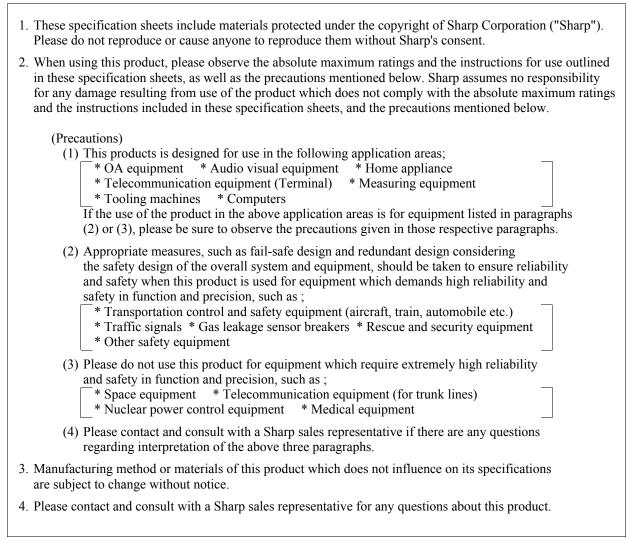
Date

By

Y.Inada, Department General Manager A1249 Project Team ELECTRONIC COMPONENTS AND DEVICES GROUP SHARP CORPORATION

\* This specification is reference.

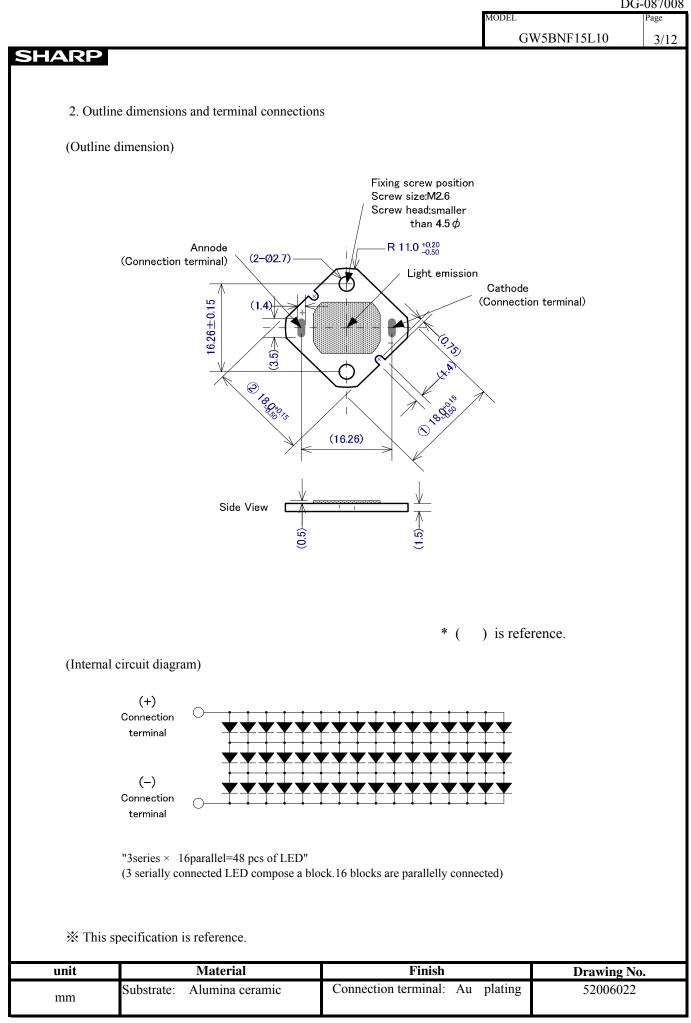
# PRODUCT NAMELight Emitting Diode ModuleMODEL No.GW5BNF15L10



\* This specification is reference.

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HARP	GW5BNF15L10	2/1
<u>GW5BNF15L10 Specific</u>	cation	
<ol> <li>Application         This specification applies to the light emitting diode module Mo         [White (from InGaN Blue LED chip + Phosphor) LED module]         Main use : Illumination     </li> </ol>		
2. Outline dimensions and terminal connections	Refer to the attached sheet Page 3.	
B. Ratings and characteristics	Refer to the attached sheet Page 4 $\sim 6$	í.
3-1. Absolute maximum ratings		
3-2. Electro-optical characteristics		
3-3. Derating Curve		
3-4. Characteristics Diagram		
4. Reliability	Refer to the attached sheet Page 7	
4-1. Test items and test conditions	refer to the attached shoet ruge .	
4-2. Failure judgment criteria		
5. Quality level	Refer to the attached sheet Page 8.	
5-1. Inspection method		
5-2. Description of inspection and criteria		
6. Supplement	Refer to the attached sheet Page 9. $\sim$	10.
6-1. Chromaticity coordinates		
6-2. Packing		
6-3. Label		
6-4.Indication to the product		
7. Precautions for use	Refer to the attached sheet Page 11 $\sim$	- 12
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* This specification is reference.		
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3. Ratings and characteristics

3-1. Absolute maximum ratings

Item	Symbol	Rating	Unit
Power dissipation *1	Р	8.0	W
Forward current *1	$I_{\rm F}$	700	mA
Reverse Voltage	V <sub>R</sub>	-15	V
Operating temperature *2	Topr	-30~+90	°C
Storage temperature	Tstg	-40∼+100°C	°C

\*1 Power dissipation and forward current are the value when the module temperature is set lower than the rating by using an adequate heat sink.

\*2 Operating temperature is fixed to the temperature of module's external part.

(Not an ambient temperature)

The derating curve in the next page is applied to the operating current.

### 3-2. Electro-optical characteristics

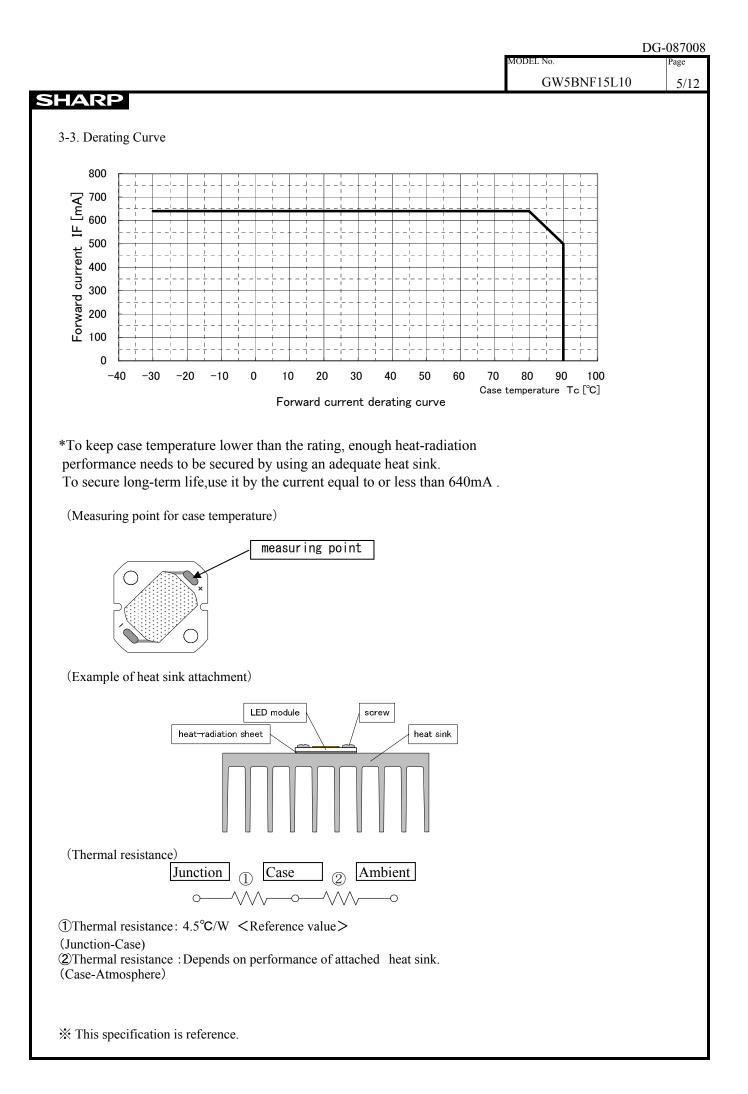
				Tc	=25 °C
Symbol	Condition	Min.	Тур.	Max.	Unit
V <sub>F</sub>	IF=640mA	8.5	(10.2)	11.5	V
φ	IF=640mA	260	(350)	-	lm
X	IF=640mA	-	0.316	-	
У		-	0.324	-	
Tc		(6000)	6500	(7000)	Κ
	V <sub>F</sub> φ           x           y	$\begin{array}{c c} V_{F} & IF=640mA \\ \phi & IF=640mA \\ \hline x & IF=640mA \\ \hline y & \end{array}$	$\begin{tabular}{ c c c c c c c c c c c c c c c c c c c$	$\begin{tabular}{ c c c c c c c c c c c c c c c c c c c$	$\begin{tabular}{ c c c c c c c c c c c c c c c c } \hline Symbol & Condition & Min. & Typ. & Max. \\ \hline V_F & IF=640mA & 8.5 & (10.2) & 11.5 \\ \hline \phi & IF=640mA & 260 & (350) & - \\ \hline \phi & IF=640mA & - & 0.316 & - \\ \hline y & & - & 0.324 & - \\ \hline \end{tabular}$

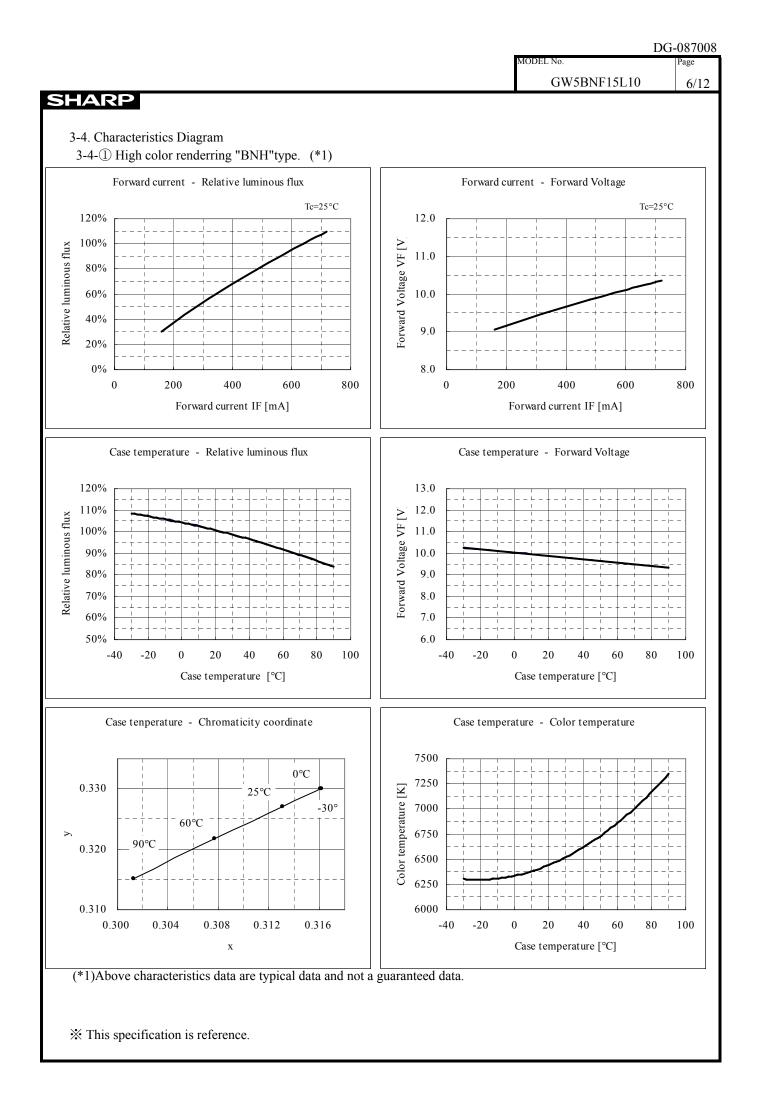
) is reference. \* (

(\*3) Monitored by 8 inch integrating sphere of Sharp Standards. (After 20 ms drive) (Tolerance:  $\pm 15\%$ )

(\*4) Monitored by 8 inch integrating sphere of Sharp Standards Measured by Otsuka electronics MODEL LE-3400 (After 20 ms drive) (Tolerance: x, y:  $\pm 0.02$ )

\* This specification is reference.





### 4. Reliability

The reliability of products shall be satisfied with items listed below.

4-1	. Test items and test c	onditions	Confide	nce leve	l: 90%
No.	Test items	Test conditions	Samples	Defective	LTPD
			n	С	(%)
1	Temperature	-40 °C(30 min)~+100 °C(30 min), 30 times			
	cycle		11	0	20
2	High temp and high	Ta*=+60°C, RH=90%, t=1,000h			
	humidity storage		11	0	20
3	High temperature	$Ta^{*}=+100^{\circ}C, t=1,000h$			
	storage		11	0	20
4	Low temperature	Ta*= -40 °C, t=1000h			
	storage		11	0	20
5	Operating test	Tc=60 °C, IF=640mA, t=1,000h			
			11	0	20
6	Mechanical shock	$15,000 \text{ m/s}^2, 0.5 \text{ ms}$			
	test	$\pm X \cdot \pm Y \cdot \pm Z$ direction, 3 times	5	0	50
7	Variable frequency	$200 \text{ m/s}^2$ , $100 \sim 2,000 \sim 100 \text{ Hz}$ / sweep for 4 min.			
	vibration	$X \cdot Y \cdot Z$ direction, 4 times	5	0	50

4-2. Failure judgment criteria

	. i anai e Jaaginene en		
No.	Parameter	Symbol	Failure judgment criteria (*2)
1	Forward voltage	V <sub>F</sub>	$V_F > U.S.L \times 1.1$
2	Luminous flux	Φ	$\Phi \le$ Initial value × 0.5, $\Phi \ge$ Initial value × 2.0

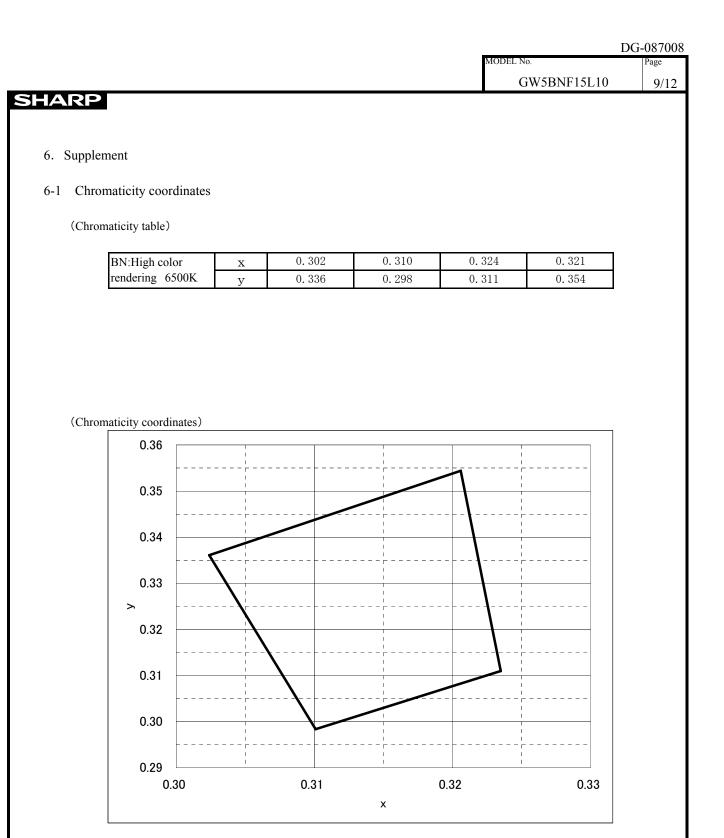
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5. Incoming inspection		
5-1. Inspection method		
A single sampling plan, normal inspection S-4 based on ISO 2	2859-1 shall be adopted.	

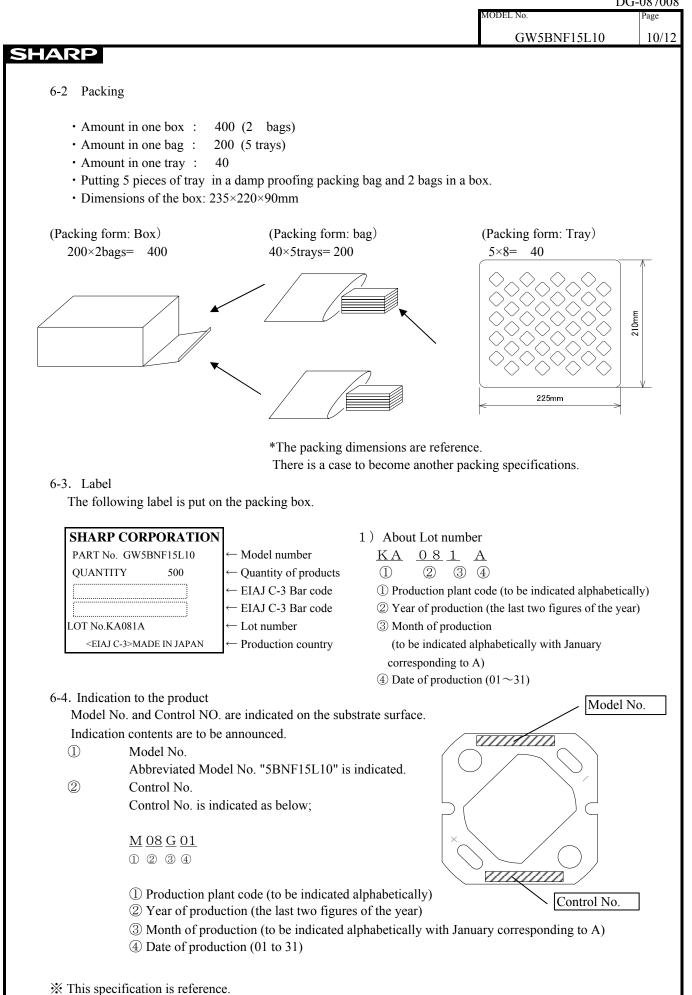
5-2. Description of inspection and criteria

No.	Inspection items	Criteria	Defect	AQL
1	Emission	No emission	Major defect	0.1%
2		Not conforming to the specification (Forward voltage, Luminous flux and Chromaticity)		
3	Outline dimensions	Not conforming to the specification (Outline dimensions of ①、② in page3)	Minor defect	0.4%
4	Appearance	Nonconformity observed in product appearance is determined as good product except that electro-optical characteristics is affected by.	dereet	

\*Products with removable foreign material attached on is not determined to be defective.



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	GW5BNF15L10	11/
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cautions		
① Storage conditions		
Please follow the conditions below.		
•Before opened: Temperature $5 \sim 30^{\circ}$ C, humidity less than $60\%$ RH		
•After opened : Temperature $5 \sim 30^{\circ}$ C, humidity less than 60%RH (Please a	pply soldering within 1 week.)	)
•Avoid exposing to air with corrosive gas.		
If exposed, electrode surface would be damaged, which may affect soldering	ıg.	
② Usage conditions		
The products are not designed for the use under any of the following conditi	ons.	
Please confirm their performance and reliability well enough if you use under	er any of the following condition	ons;
• In a place with a lot of moisture, dew condensation, briny air, and corrosiv	e gas	
(Cl, $H_2S$ , $NH_3$ , $SO_2$ , $NO_X$ , etc.).		
•Under the direct sunlight, outdoor exposure, and in a dusty place.		
•In water, oil, medical fluid, and organic solvent.		
③ Heat radiation		
If the forward surrout (IE) is explicit to single state module at 260m A there?	a a right of domoging modulo	

If the forward current(IF) is applied to single-state module at 360mA, there is a risk of damaging module or emitting smoke.

Equip with specified heat radiator, and avoid heat stuffed inside the module.

Applying thermal conductive sheet or grease between module and heat radiator enables heat to radiate effectively.

(4) Installation

Material of board is alumina ceramic. If installed inappropriately, trouble of no radiation may occur due to board crack. Please take particular notice of install method.

Further information on installation, refer to the following cautions.

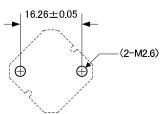
Apply ether screws or adhesives, or both of them when installed to heat radiator.

In case of applying adhesive only, check the effectiveness before fixing.

In case of screw, apply thread locker in order to prevent loosening.

If LED comes off from the heat radiator, unusual temperature rise entails hazardous phenomena including device deterioration, coming off of solder at leads, and emitting smoke.

Refer to recommended dimensions when installing with screws.



• Screw torque: Within 0.2Nm

If it is inefficient to tighten screws, apply locker to prevent loosening.

- It is recommended to apply screws which use low corrosive materials such as Stainless steel.
- Avoid applying flat-head screws, which cause board crack due to applying stress to screw holes. Avoid convexly uneven boards.
- Those convex boards are subject to crack when tightening screws.
- It is recommended to apply thermal conductive sheet or grease with adhesiveness and heat radiatingadhesives, because of thermal and mechanical combination between module and heat radiator. However, depending on their thickness, board crack may be entailed by warped board, which is caused when tightening screws. So please check your actual conditions carefully as for the screw torque.

\* This specification is reference.

7. Preca

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(5) Module surface strength	
Module surface is subject to mechanical stress. Applying stres and inside-failure.	s to surface of modules results in damage or
6 Connecting method	
In case of solder connecting method, apply solder to the leads	3
by soldering iron with thermo controller (tip temperature 380°	°C), within 10seconds per one place.
Put the board on materials whose conductivity is poor enough	not to radiate heat of soldering.
Avoid touching yellow phosphor with soldering iron.	
This product is not designed for reflow and flow soldering.	
⑦ Static electricity	
This product is subject to static electricity, so take measures to	o cope with it.
Install circuit protection device to drive circuit, if necessary.	
(8) Drive method	
Module is composed of LEDs connected in both series and part	
runs off more than specified current amount due to lowered VI	F caused by temperature rise.
Constant current power supply is recommended to drive.	
Any reverse voltage cannot be applied to LEDs when they are	-
Design a circuit so that any flow of reverse or forward voltage	can not be applied to LEDs when they are
out of operation.	
(9) Cleaning	
Avoid cleaning, since silicone resin is eroded by it.	
(1) Color-tone variation Characteristic of this area duct is monitored has into another or here	a right often the exercise
Chromaticity of this product is monitored by integrating spher	•
Chromaticity varies depending on measuring method, light spi Please verify your actual conditions before use.	read condition, of amolent temperature.
<ol> <li>Safety</li> </ol>	
Looking directly at LEDs for a long time may result in hurt yo	nur eves
In case that excess current(over ratings) are supplied to the dev	5
heat generation, emitting smoke, or catching fire can be caused	
Take appropriate measures to excess current and voltage.	
In case of solder connecting method, there is a possibility of f	fatigue failure by heat
in our of solution connecting interious, there is a possibility of t	
Please fix the leads in such case to protect from short circuit of	
Please fix the leads in such case to protect from short circuit of Please confirm the safety standards or regulations of applicati	on devices